

SOT108-2

plastic small outline package; 14 leads; body width 3.9 mm;
body thickness 1.47 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO14
Package type industry code	SO14
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-012
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.55	-	8.65	8.75	mm
E	package width	3.8	-	3.9	4	mm
A	seated height	[tbd]	-	1.75	1.75	mm
A ₂	package height	1.4	-	1.47	1.55	mm
n ₂	actual quantity of termination	-	-	14	-	

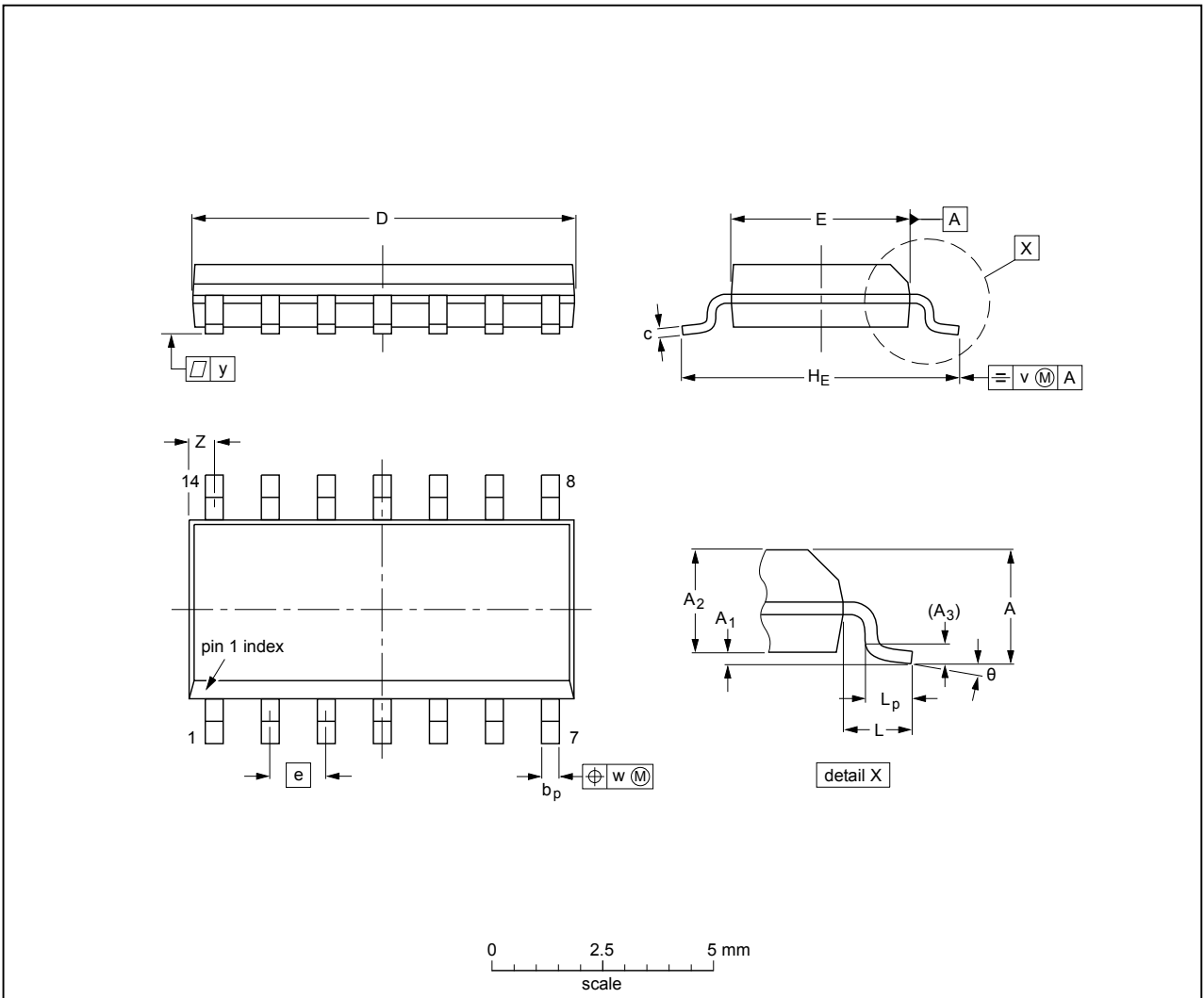


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2. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm; body thickness 1.47 mm

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	v	w	y	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.55 1.40	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.061 0.055	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT108-2		MS-012				01-05-29 03-02-19

Fig. 1. Package outline SO14 (SOT108-2)

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3. Soldering

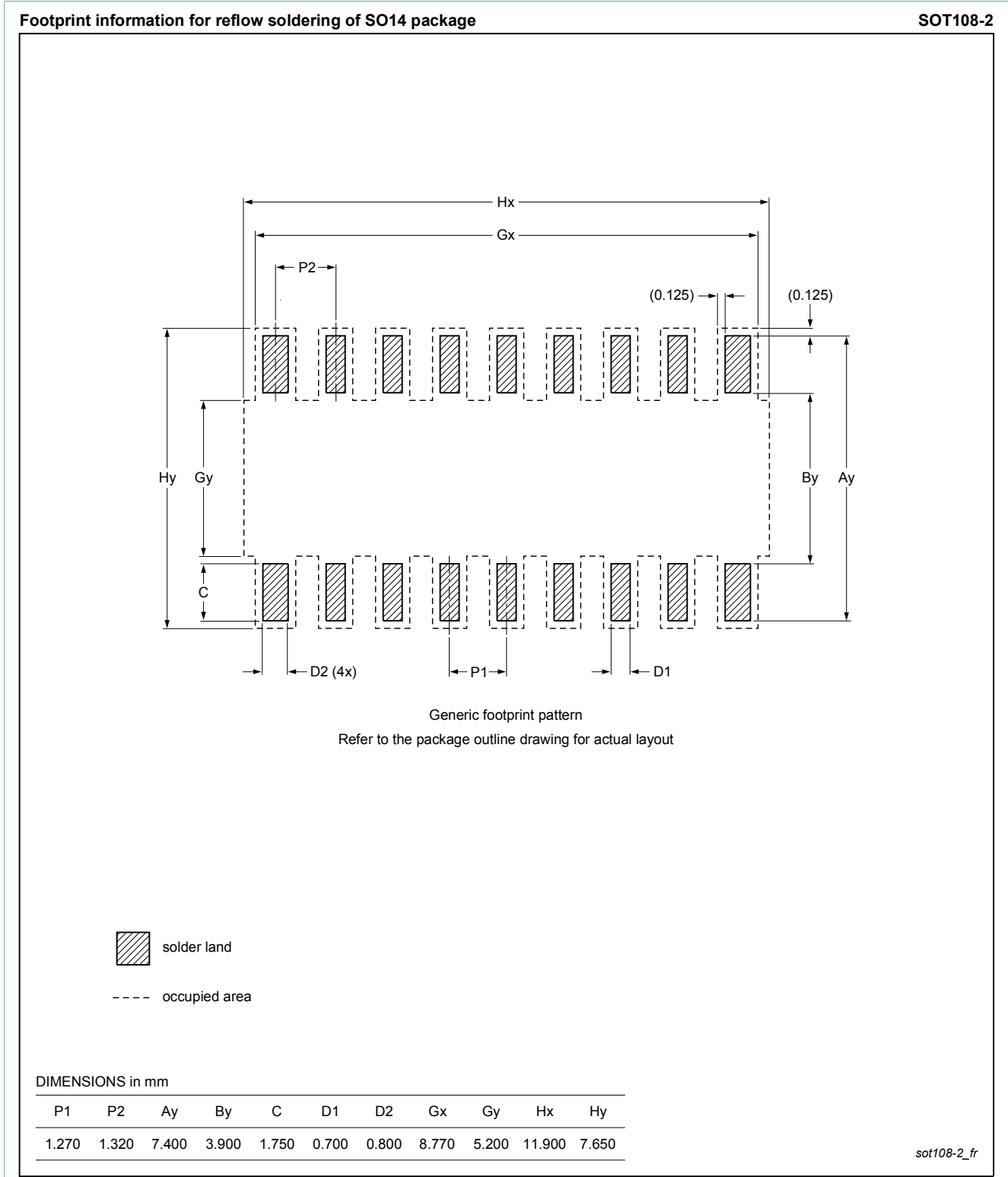


Fig. 2. Reflow soldering footprint for SO14 (SOT108-2)

plastic small outline package; 14 leads; body
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4. Legal information

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